

SS32 - S310

Features

- · Metal to silicon rectifiers, majority carrier conduction.
- Low forward voltage drop.
- · Easy pick and place.
- High surge current capability.



SMC/DO-214AB COLOR BAND DENOTES CATHODE

Schottky Rectifiers

Absolute Maximum Ratings* T_A = 25 ℃ unless otherwise noted

| Symbol | Parameter | Value | | | | | | | | Units |
|--------------------|--|-------|----|----|----|----|----|----|-----|-------|
| - | | 32 | 33 | 34 | 35 | 36 | 38 | 39 | 310 | |
| V_{RRM} | Maximum Repetitive Reverse Voltage | | 30 | 40 | 50 | 60 | 80 | 90 | 100 | V |
| I _{F(AV)} | Average Rectified Forward Current, @ T _A = 75 °C 3.0 | | | | Α | | | | | |
| I _{FSM} | Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave | | | Α | | | | | | |
| T _{sta} | Storage Temperature Range -55 to +150 | | | °C | | | | | | |
| T _J | Operating Junction Temperature -55 to +150 | | | °C | | | | | | |

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

| Symbol | Parameter | Value | Units | |
|-----------------|---|-------|-------|--|
| P_{D} | Power Dissipation | 2.27 | W | |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient * | 55 | °C/W | |
| $R_{\theta JL}$ | Thermal Resistance, Junction to Lead | 17 | °C/W | |

^{*}Device mounted on FR-4 PCB 0.55 x 0.55" (14 x 14 mm).

Electrical Characteristics $T_A = 25 \, ^{\circ}\!C$ unless otherwise noted

| Symbol | pol Parameter | | Device | | | | | | | | Units |
|----------------|--|----------------------|--------|----|---------|----|----|----|----|-----|-------|
| | | | | 33 | 34 | 35 | 36 | 38 | 39 | 310 | |
| V _F | Forward Voltage @ 3.0 A | | 500 | | 750 850 | | | | mV | | |
| I _R | Reverse Current @ rated V _R T _A = 25°C | | 0.5 | | | | | | | mA | |
| | | $T_A = 100^{\circ}C$ | | 20 | | | | 10 | | | mA |

Schottky Rectifiers

(continued)

Typical Characteristics

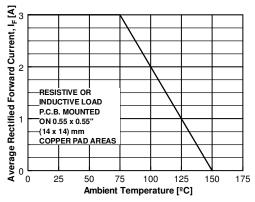


Figure 1. Forward Current Derating Curve

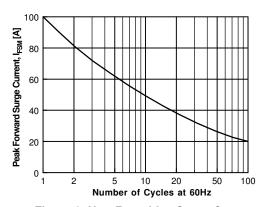


Figure 2. Non-Repetitive Surge Current

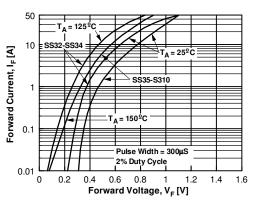


Figure 3. Forward Voltage Characteristics

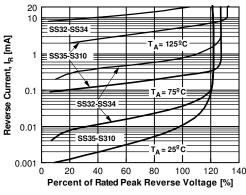


Figure 4. Reverse Current vs Reverse Voltage

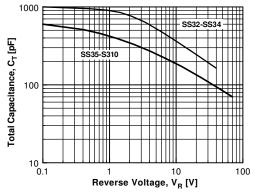


Figure 5. Total Capacitance

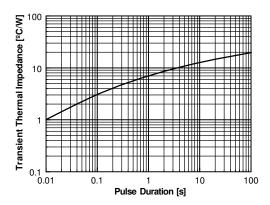


Figure 6. Thermal Impedance Characteristics

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|--------------------------|---------------------------|---|
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